HB650I25

Intel® Alder Lake-S Chip, Support LGA1700 CPU, DDR4 up to 64GB, support DC 12~19V input

Front

HDD LED
Power Button
4 x USB 2.0
Reset Button
FAN Connector
Power LED

Rear

DC-in
2 x RS-232/422/485
2 x RS-232
GND Hold
HDMI®
DP
2 x RJ45
Mic-in
Line-Out
2 x USB 3.2
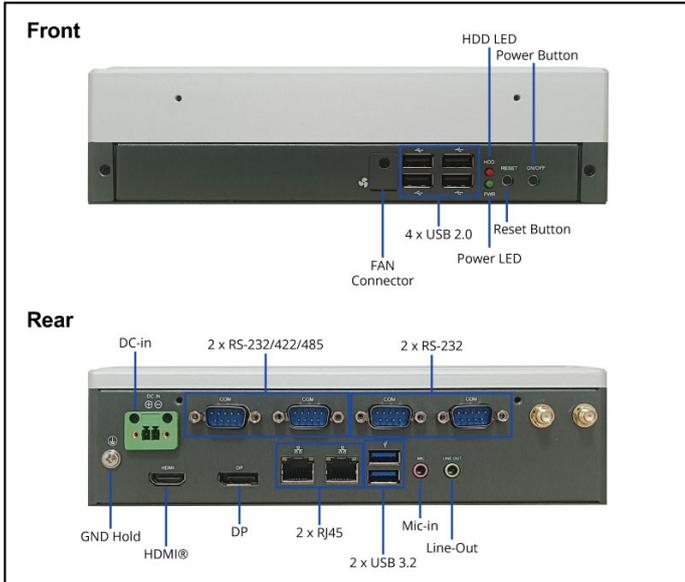
Features

- ■ Intel® 12th/13th/14th LGA1700 Socket Core I3,I5,I7 Pentium Processor (Max 65W)
- ■ Intel® Alder Lake-S H610 Chip
- ■ Support DDR4 3200 Max 64GB
- ■ 2 x Realtek® RTL8111H GbE
- ■ 1 x M.2 M-key (2280, PCIex4 interface) support NVME, 1 x M.2 E key (2230, CNVi/PCI-Ex1/USB2.0)
- ■ 2 x RS232/422/485 (Support 5V/12V TTL), 2 x RS232
- ■ 2 x USB3.2 (Gen.1), 4 x USB2.0
- ■ Support DP and HDMI®

Packing List

PART NUMBER	DESCRIPTION	QTY
-	HB650I25-H610-B	1
-	Power cord	1
L01AS056-F	Adapter 19V/6.32A 120W FSP120-ABBN5 tuning fork	1
HCS650MWM01B-F	WALL MOUNT KITS	1
LCSCHBFDXXX-F	Screw Pack	1
LCSCHBJC3XX-F	Screw Pack	1
HCS3XXDINRAILPS-F	DIN RAIL CLIP KYTS	1
HCFAN65X-DC1225	DC1225 FAN Expansion module (Option)	1

Specifications

SYSTEM

MB FORM FACTOR	Thin Mini-ITX
CPU	Intel® LGA1700 12/13/14th Gen Socket Processor (Formerly Alder Lake-S, TDP 65W)
CHIPSET	Intel® H610
MEMORY	2 x DDR4 3200MT/s, Dual Channel SO-DIMM, up to 64GB
BIOS	AMI Flash ROM
WAKE ON LAN	Yes
WATCHDOG TIMER	255 Levels
RTC BATTERY	Lithium Battery
OS SUPPORT	Windows® 10 (64bit) Windows® 11 (64bit) Linux

POWER

POWER REQUIREMENT	DC-in 12~19V
POWER ON MODE	AT / ATX

DISPLAY

GPU	Intel® UHD Graphics
DP	1 x DP1.4 (Max Resolution: 7680 x 4320@60Hz)
HDMI®	1 x HDMI® (Max Resolution: 4096 x 2160@30Hz)
MULTIPLE DISPLAY	Support 2 Displays

AUDIO

CODEC	Realtek ALC897
AMPLIFIER	3W

LAN

ETHERNET	2 x RJ45 for Realtek® RTL8111H GbE

SYSTEM I/O

REAR PANEL I/O	2 x RS-232/422/485 2 x RS-232 1 x MIC-in 1 x Line-out 1 x Phoenix Terminal Block 12~19V DC input 2 x WIFI Antenna Holes
FRONT PANEL I/O	1 x FAN link con 4 x USB 2.0 1 x Power LED 1 x HDD LED 1 x Reset Button 1 x Power Button

EXPANSION

M.2	1 x M-Key 2242/2280 (PCIe x4) support NVMe SSD 1 x E-Key 2230 (CNVioo/PCIe x1/USB2.0) support WiFi/BT Module

MECHANICAL

DIMENSIONS (W x D x H)	224.0 (W) x 199.0 (D) x 63.0 (H) mm

ENVIRONMENT & CERTIFICATION

SHOCK	15G, 11ms duration
VIBRATION	1 Grms/ 5~ 500Hz/ Operation
OPERATING TEMPERATURE	-20°C ~ 60°C (-4°F ~ 140°F)
STORAGE TEMPERATURE	-40°C ~ 85°C (-40°F ~ 185°F)
OPERATING HUMIDITY	10 ~ 95% @ 40°C, Non-condensing
CERTIFICATION	CE/FCC Class A
ESG DECLARATION	ErP EU RoHS

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Note: All specifications are subject to change without notice.

Ordering Information

PART NUMBER	HB650I25-H610-B
CPU	Intel® Alder Lake-S Processor H610
MEMORY	2 x DDR4 SO-DIMM, up to 64GB
POWER REQUIREMENT	DC-in 12~19V
GPU	Intel® UHD Graphics
DP	1 x DP
HDMI	1 x HDMI®
MULTIPLE DISPLAY	Support 2 Displays
ETHERNET	2 x GbE
I/O	2 x USB 3.2
I/O	4 x USB 2.0
I/O	2 x RS-232/422/485
I/O	2 x RS-232
I/O	1 x Phoenix Terminal Block 12~19V DC input
I/O	2 x WIFI ANT
I/O	1 x FAN link con
I/O	1 x MIC-in
I/O	1 x Line-out
I/O	1 x Power LED
I/O	1 x HDD LED
I/O	1 x Reset button
I/O	1 x Power button
M.2	1 x M-Key 2242/2280
M.2	1 x E-Key 2230
OPERATING TEMPERATURE	-20°C ~ 60°C (-4°F ~ 140°F)

Note: All specifications are subject to change without notice.